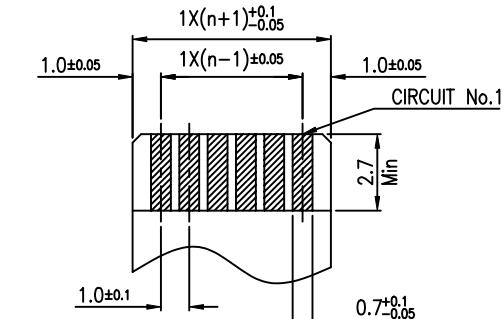


CKT	DIM.A	DIM.B	DIM.C
006	5.00	7.06	10.7
008	7.00	9.06	12.7
010	9.00	11.06	14.7
012	11.00	13.06	16.7



APPLICABLE FPC RECOMMENDED DIM.
(THICKNESS: 0.3 ± 0.03)

NOTES:

1. MATERIAL:
1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0.
1.2 ACTUATOR: THERMOPLASTIC, HIGH TEMP., UL94V-0.
1.3 CONTACT: COPPER ALLOY
1.4 FITTING NAIL: COPPER ALLOY
2. FINISH:
UNDER PLATING: 50μ MIN. NICKEL OVERALL
CONTACT AREA AND SOLDER TAIL: GOLD FLASH OVERALL
FITTING NAIL:
UNDER PLATING: 50μ MIN. NICKEL OVERALL
MATTE TIN PLATING 100μ MIN. OVERALL
3. REFLOW SOLDER CAPABLE TO 260°C PEAK TEMP.
FOR 10 SECONDS MAX.
4. SPEC. PLS. REFER TO GS-12-579.
5. PACKAGE PLS. REFER TO GS-14-1331.
6. PART NUMBER DESCRIPTION:

10089709-XXX 0 1 0 LF
NO OF CONTACTS(CKT) LEAD FREE
PACKING COLOR
0: TAPE & REEL X: HOUSING ACTUATOR
 0: NATURAL BLACK
PLATING
1: GOLD FLASH OVERALL

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY	 www.fciconnect.com
ltr	ecn no	dr	date	linear	angles		
A	T08-1182	WL	11/06/08	.X ± 0.25	.XX ± 0.15	projection	title 1.0mm FPC CONN. SMT R/A B/C TYPE
B	T08-1196	WL	12/10/08	.XXX ± 0.10	0° ± 2°	MM	product family FPC
C	T09-1001	WL	01/05/09	dr LEIF SHEN	08-06-18	size	code SNG
D	T09-1005	WL	01/20/09	engr DENNIS GOH	08-10-20	dwg no	sheet 1 of 1
E	T09-1132	WL	10/15/09	chr DENNIS GOH	08-10-20	scale	A4 10089709
F	T10-0046	WL	04/15/10	appd JOEY NG	08-10-20		
sheet	revision	F					
index	sheet	1					